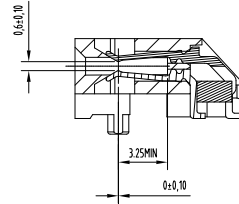
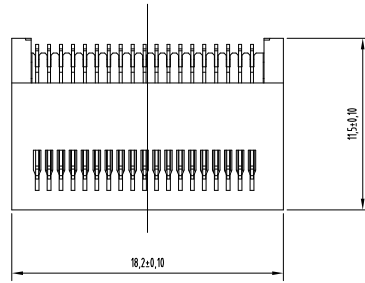
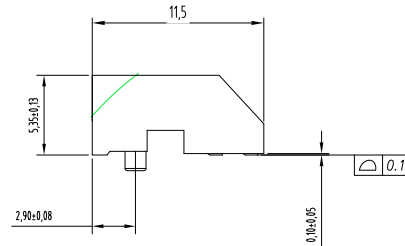
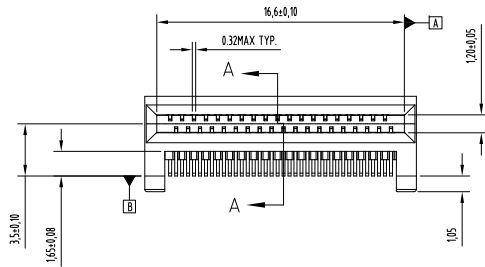


REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2022/07/05	



SECTION A-A



NOTES, UNLESS OTHERWISE SPECIFIED:

1. MATERIAL:

HOUSING: THERMOPLASTIC GLASS FILLED.

SPACER: THERMOPLASTIC GLASS FILLED.

CONTACT: COPPER ALLOY.

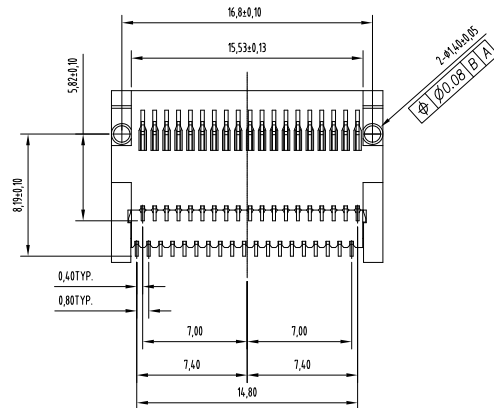
2. PLATING:

CONTACT AREA: GOLD PLATING OVER 50u"MIN. NICKLE.

SOLDER AREA: 100U"MIN. TIN OVER 50u"MIN. NICKLE.

3. PRODUCT DESIGN CONFORM TO QSFP INDUSTRY SPEC.

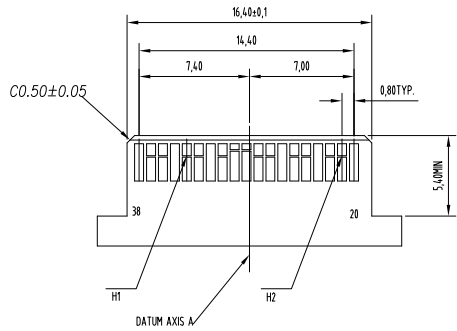
4. Harmful material control follow RoHS



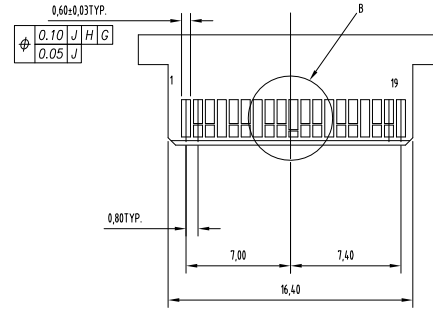
X:X ±0.25	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED
X:XX ±0.20	CHKD:	
X:XXX ±0.05	DR: James	TITLE: QSFP+ 1X1 CONNECTOR
ANGLES ±1°	UNIT: mm	PART NO.: LPSFP3802
	SCALE: 2/1	SHEET: 1/2
	REV: A	DWG NO.: LP22070501

Mechanical:

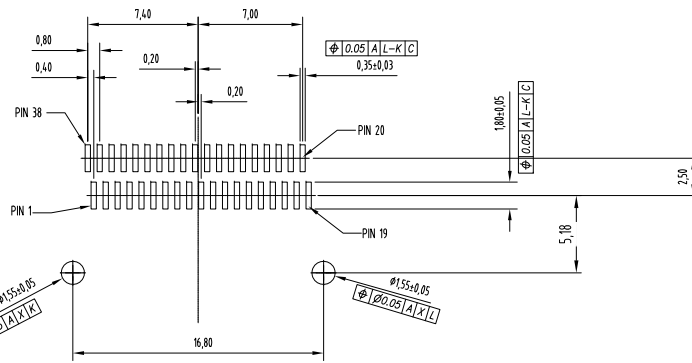
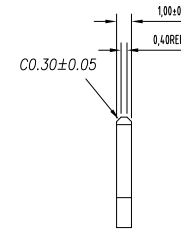
REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2022/07/05	



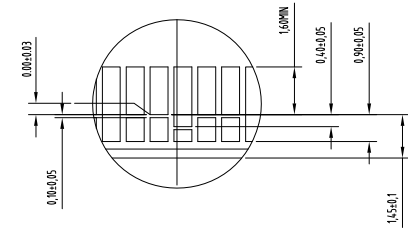
TOP VIEW OF PLUG BOARD



BOTTOM VIEW OF PLUG BOARD



PCB LAYOUT (TOP VIEW)



DETAIL-B

2:1



X:X ±0.25	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED
X:XX ±0.20	CHKD:	
X:XXX ±0.05	DR: James	TITLE: QSFP+ 1X1 CONNECTOR
ANGLES ±1°	UNIT: mm	PART NO.: LPSFP3802
	SCALE: 2/1	SHEET: 2/2
	REV: A	DWG NO.: LP22070501